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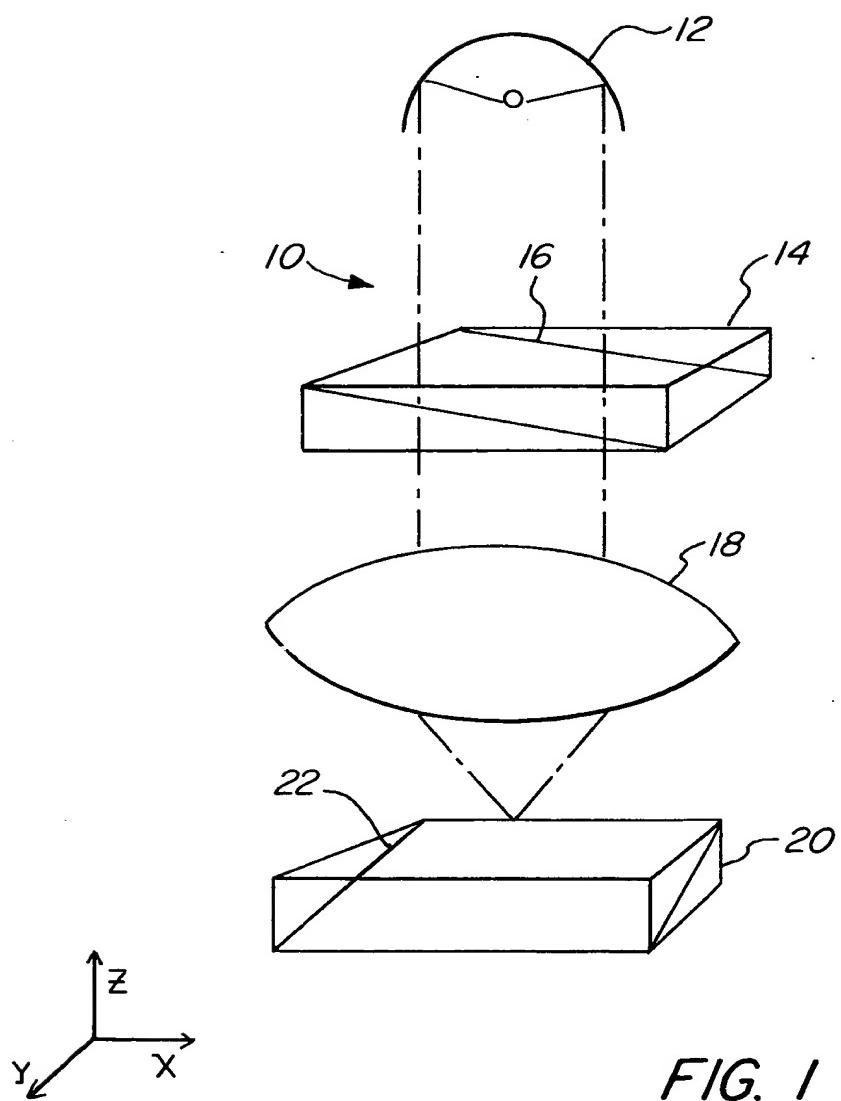
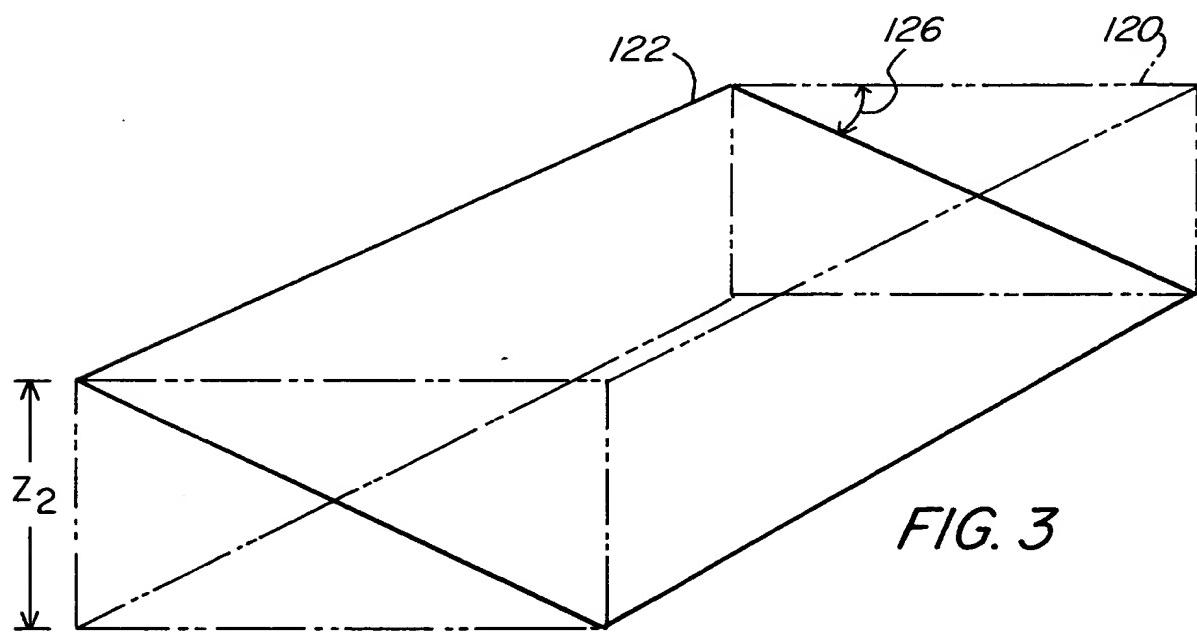
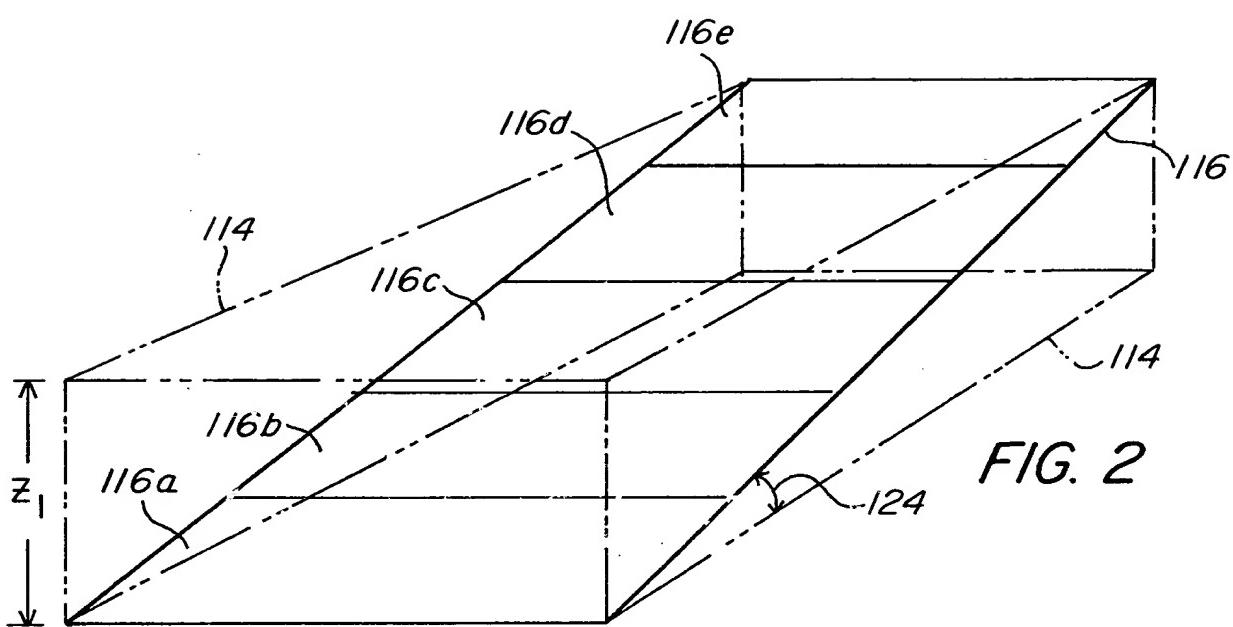


FIG. 1



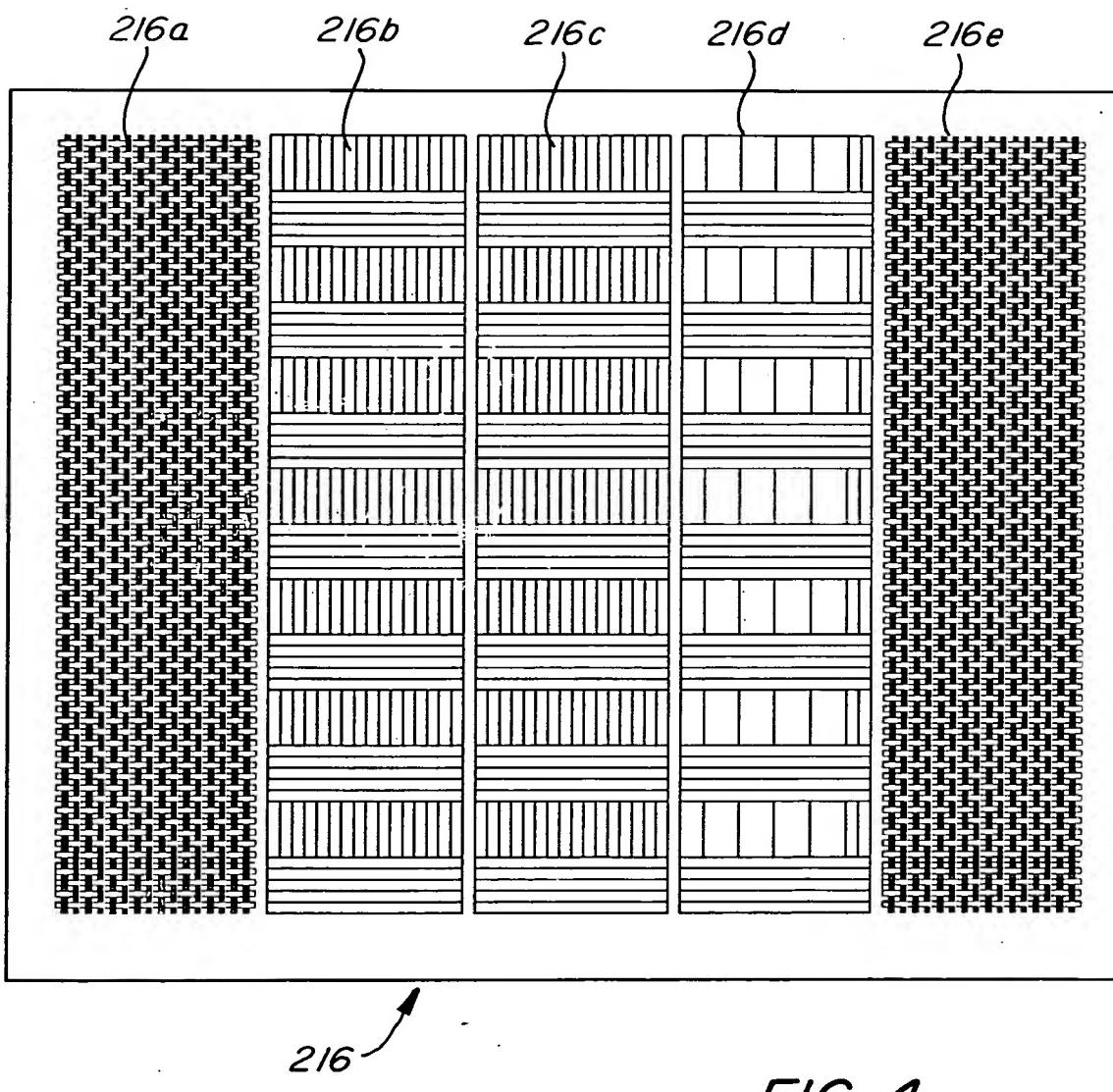


FIG. 4

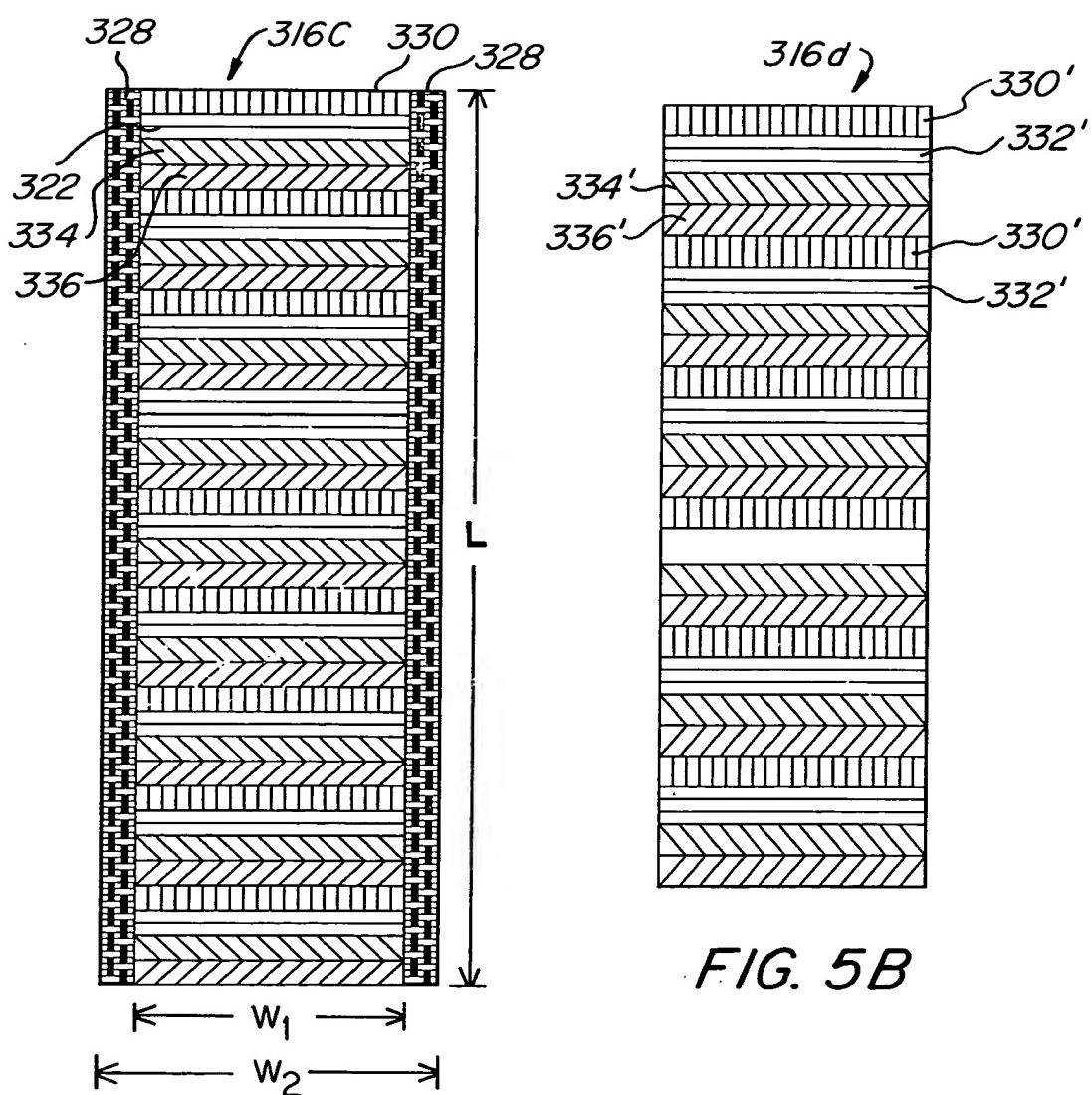


FIG. 5A

FIG. 5B

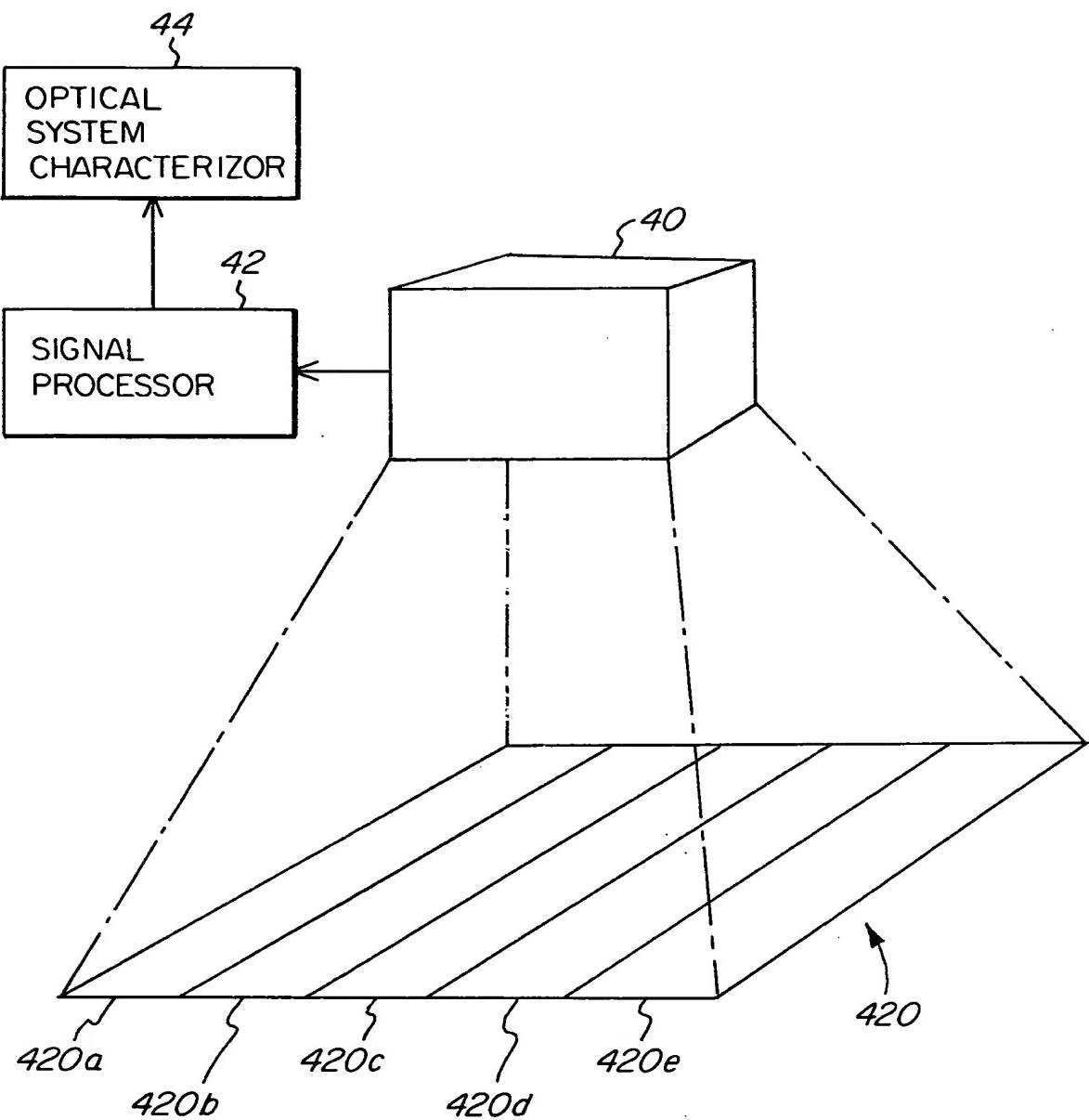


FIG. 6

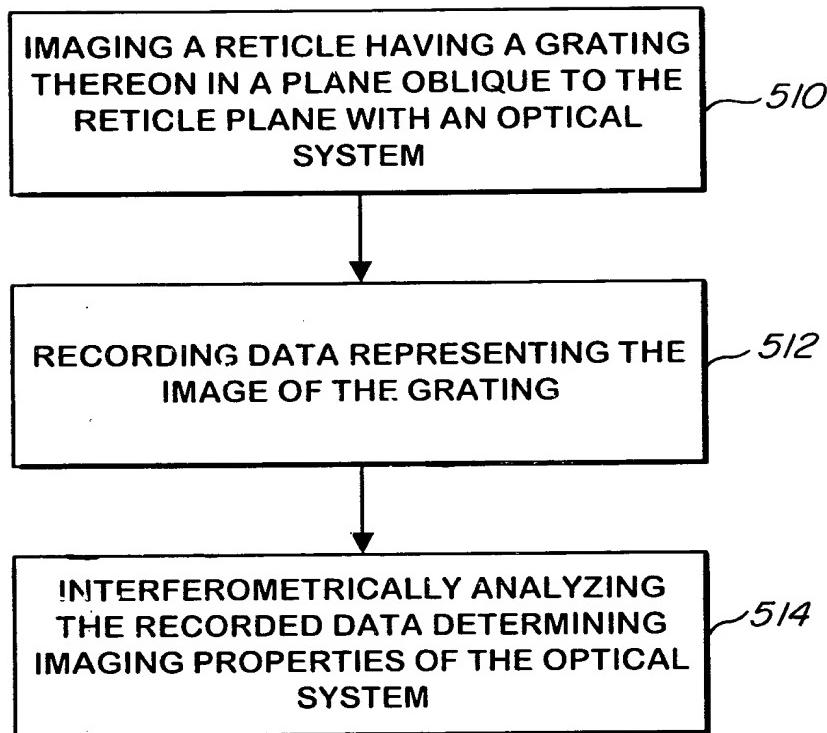


FIG. 7

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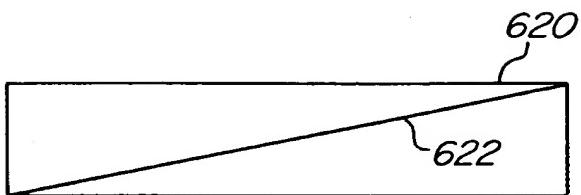


FIG. 8A

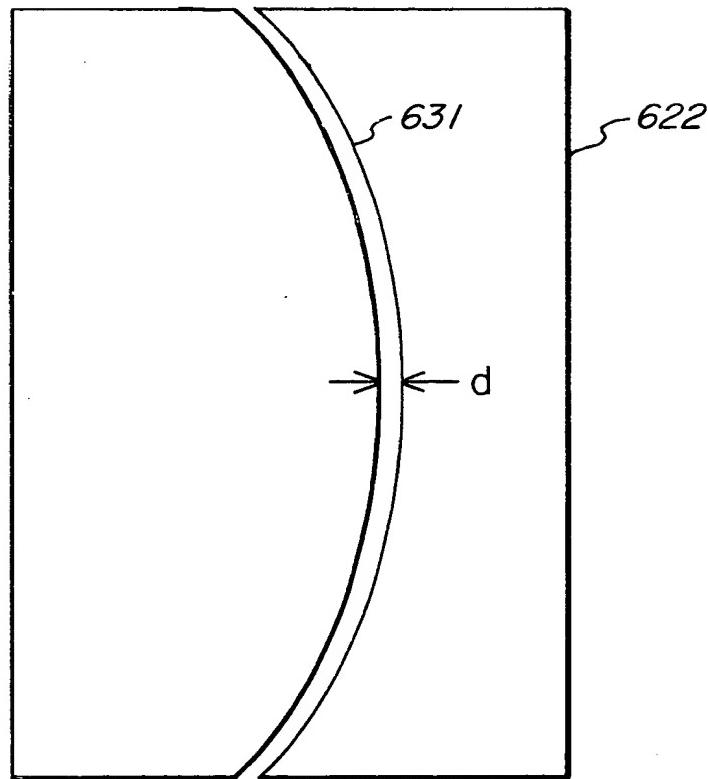
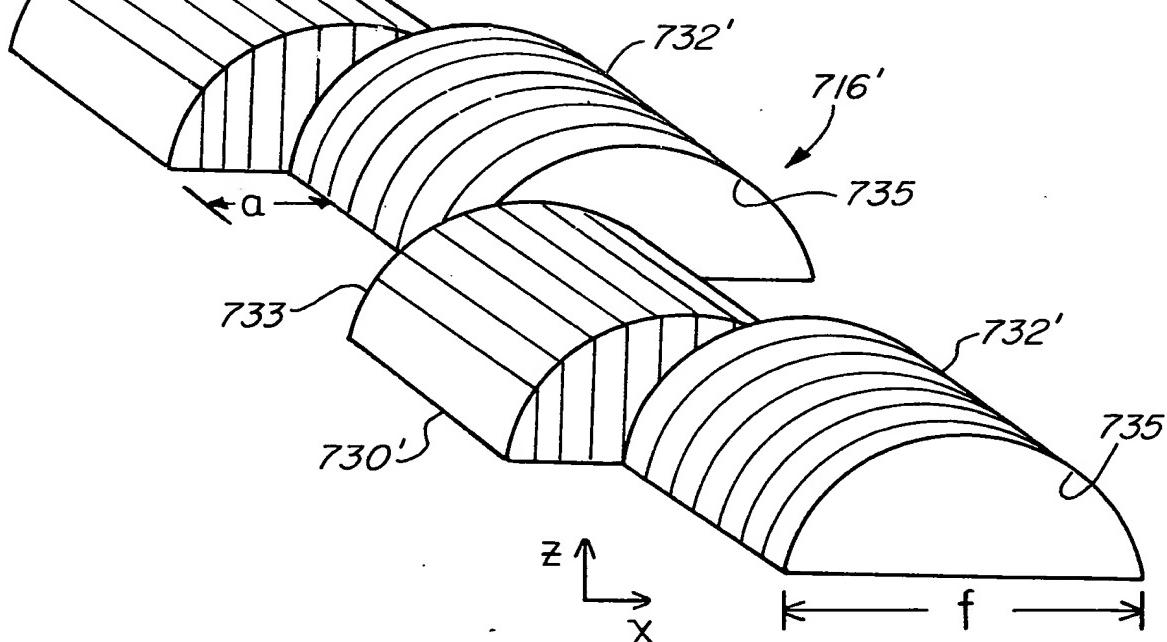
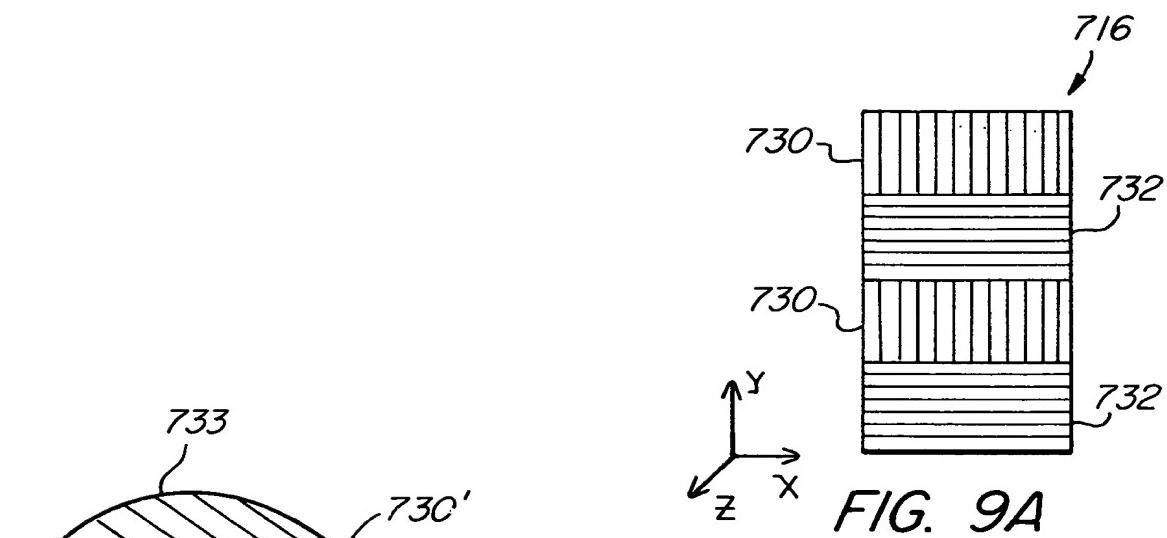


FIG. 8B



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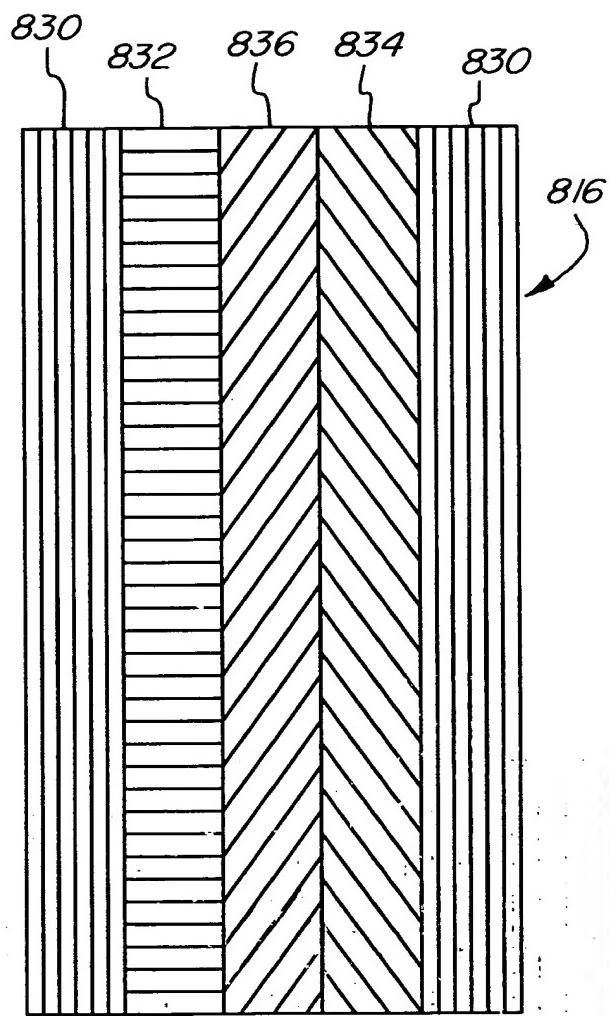


FIG. 10B

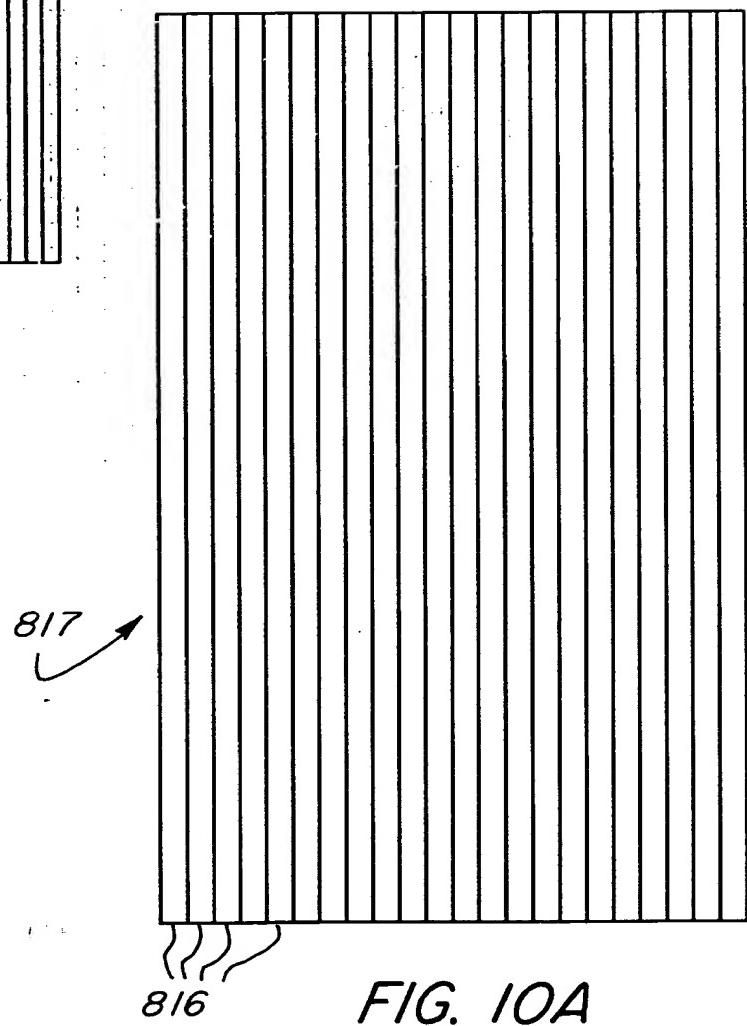
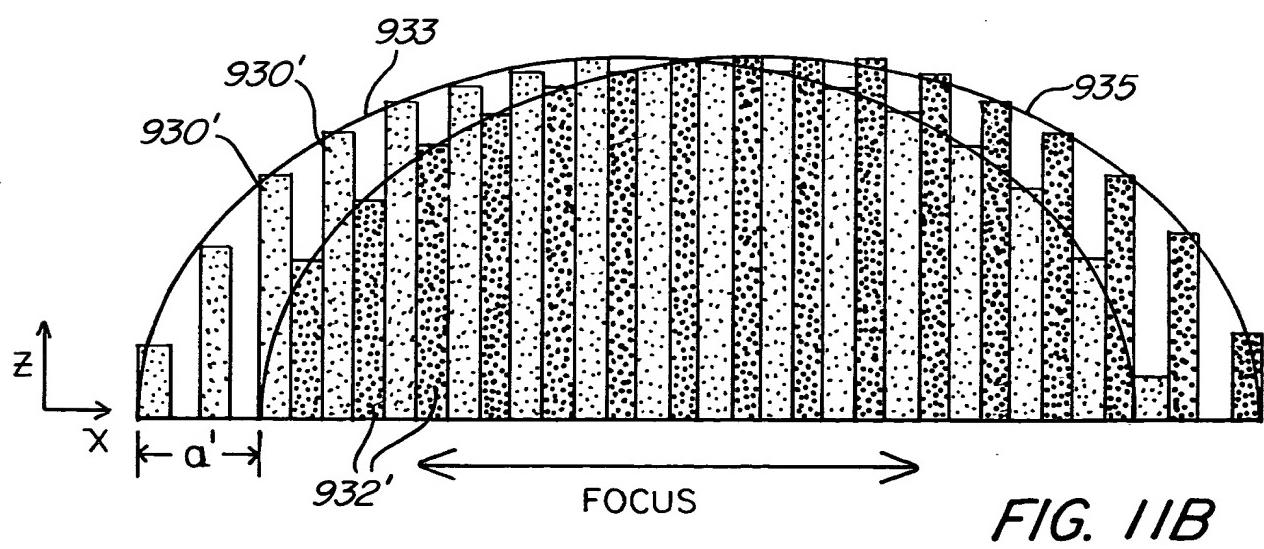
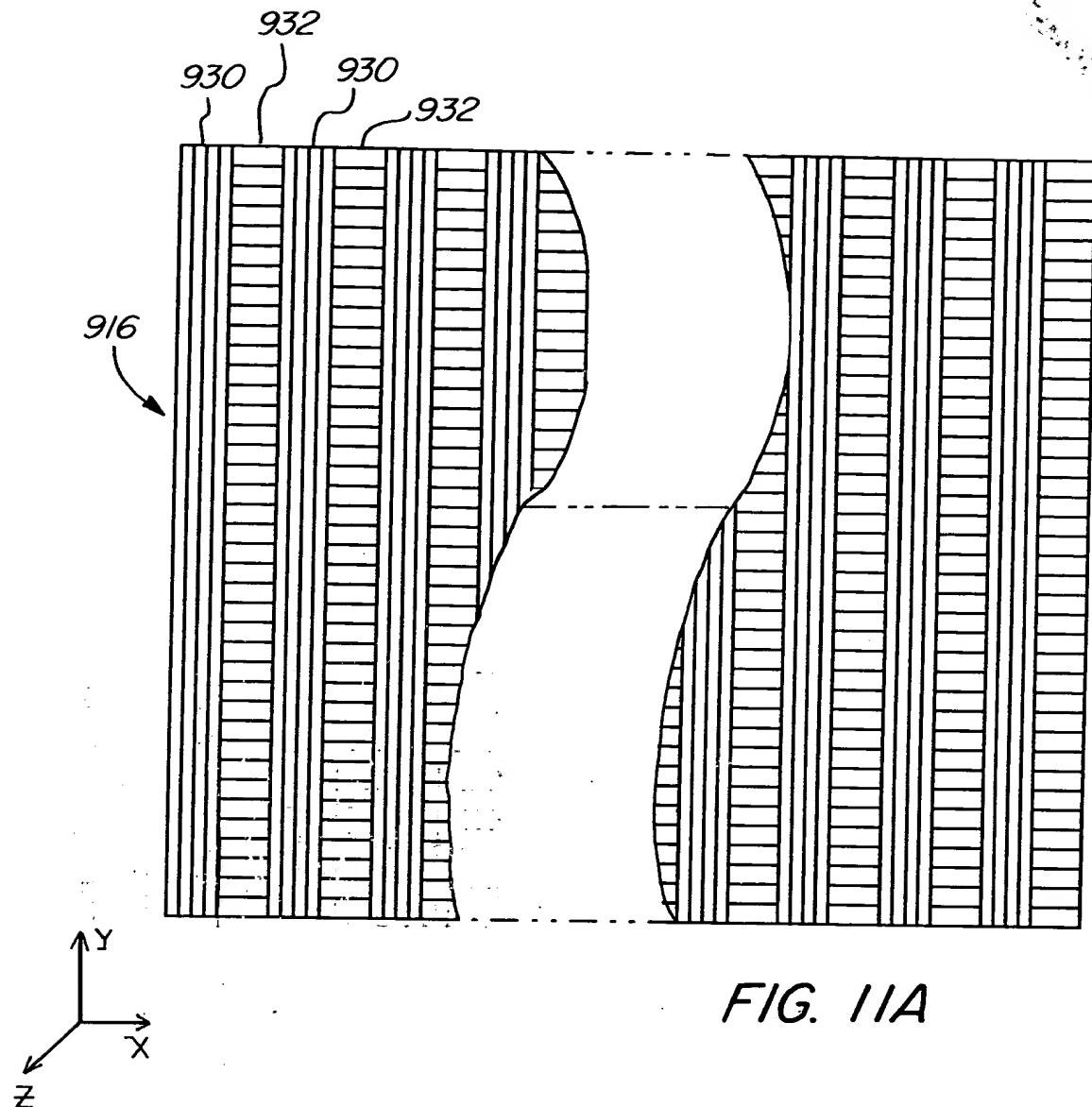


FIG. 10A



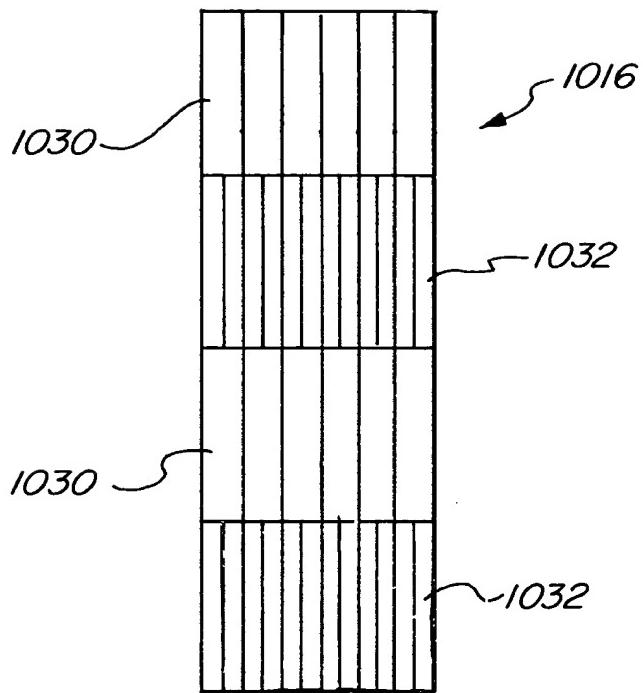


FIG. 12

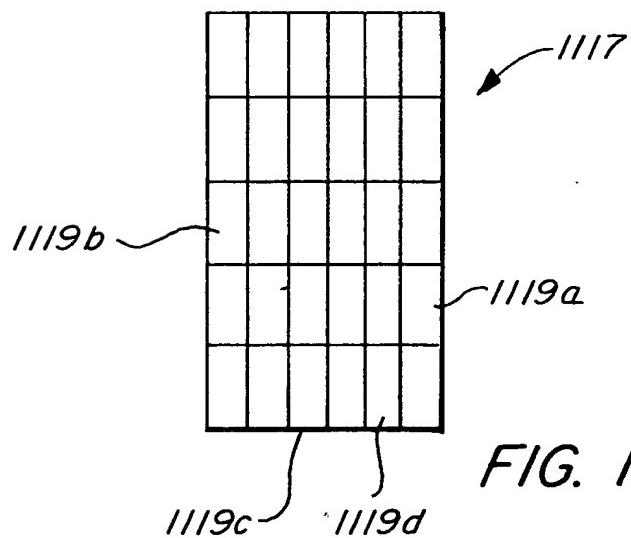


FIG. 13

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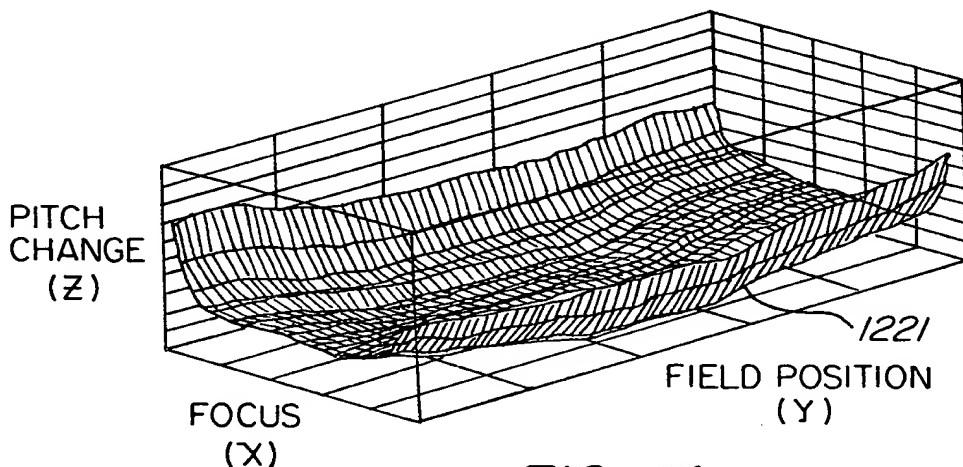


FIG. 14

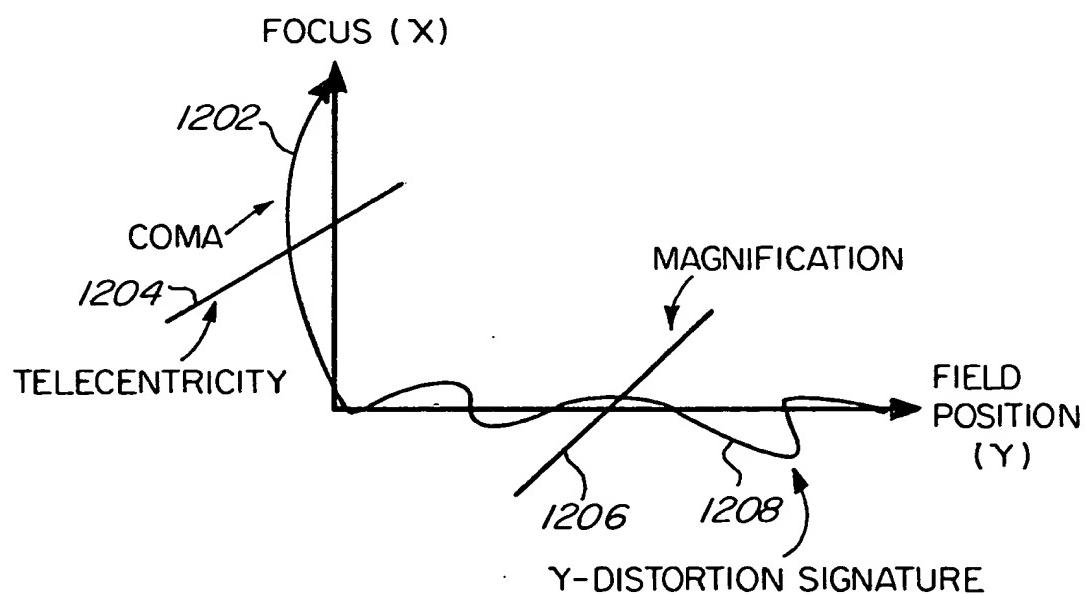


FIG. 15

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FIG. 16A

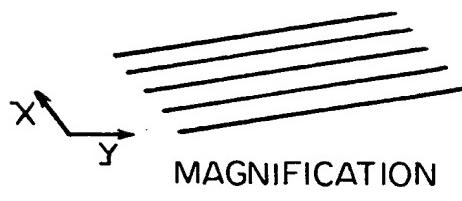


FIG. 16B

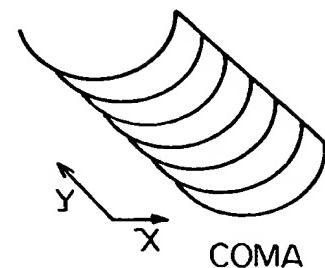


FIG. 16C

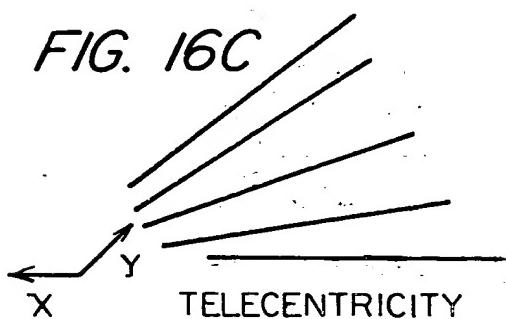


FIG. 16D

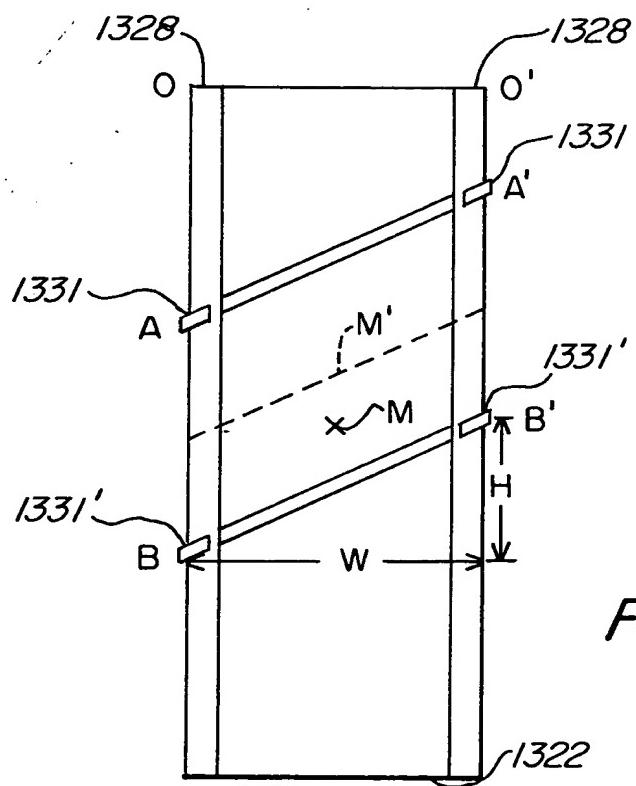
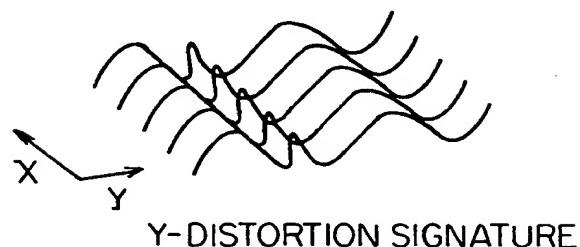


FIG. 17

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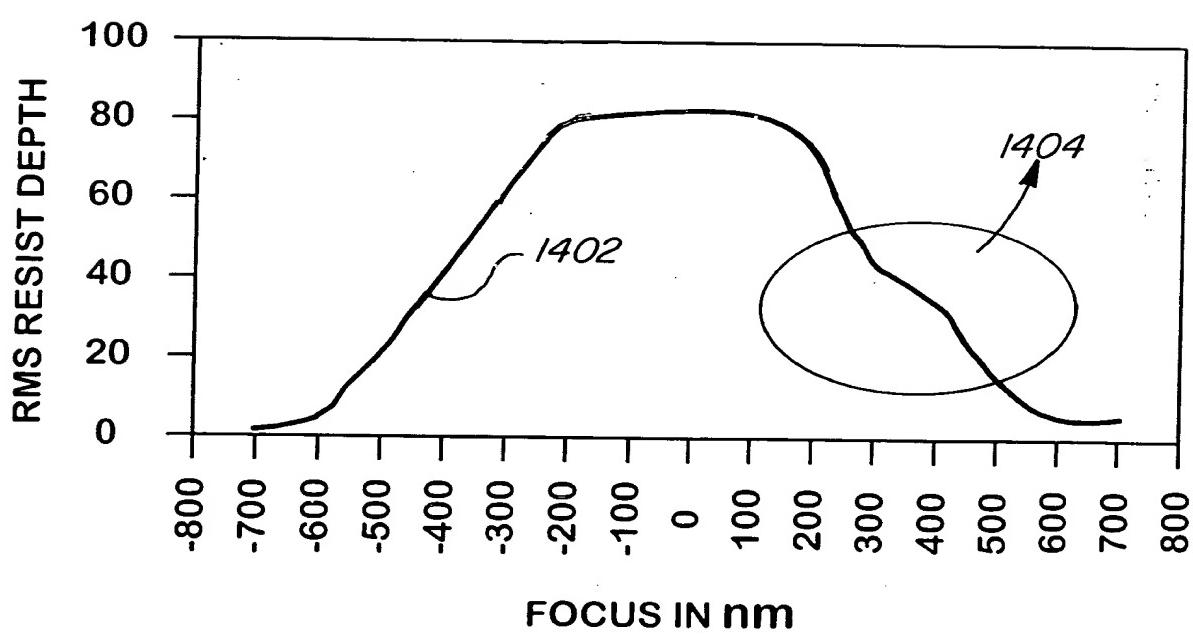


FIG. 18

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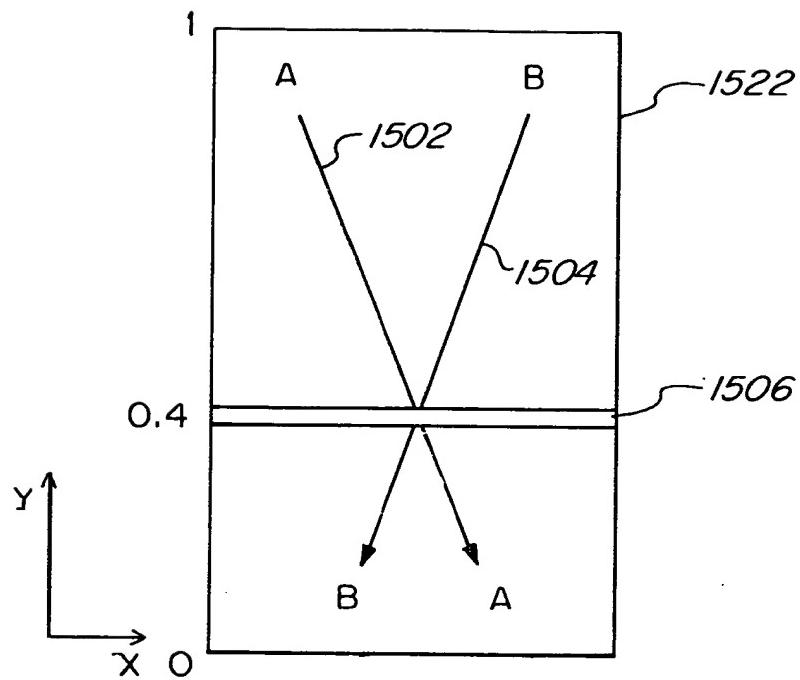


FIG. 19A

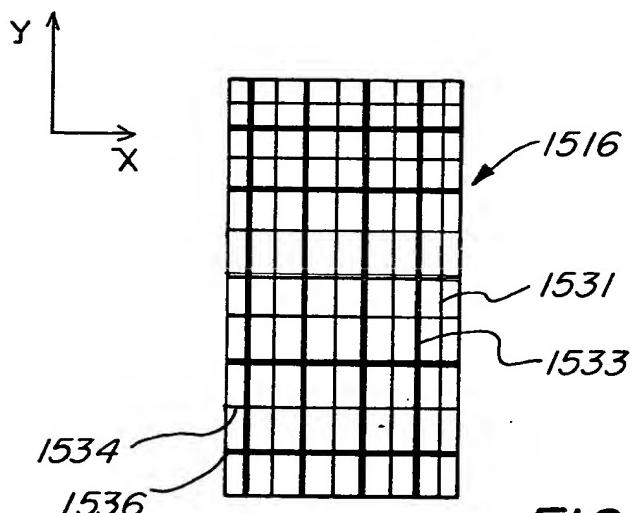


FIG. 19B